# **Dual Type D Flip-Flop**

The MC14013B dual type D flip–flop is constructed with MOS P–channel and N–channel enhancement mode devices in a single monolithic structure. Each flip–flop has independent Data, (D), Direct Set, (S), Direct Reset, (R), and Clock (C) inputs and complementary outputs (Q and  $\overline{Q}$ ). These devices may be used as shift register elements or as type T flip–flops for counter and toggle applications.

- Static Operation
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Edge-Clocked Flip-Flop Design
   Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive-going edge of the clock pulse
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4013B

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>) (Note 2.)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 3.)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \ or \ V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



http://onsemi.com

#### MARKING DIAGRAMS

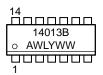


PDIP-14 P SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A



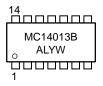


TSSOP-14 DT SUFFIX CASE 948G





SOEIAJ-14 F SUFFIX CASE 965



A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

#### ORDERING INFORMATION

Device	Package	Shipping
MC14013BCP	PDIP-14	2000/Box
MC14013BD	SOIC-14	55/Rail
MC14013BDR2	SOIC-14	2500/Tape & Reel
MC14013BDT	TSSOP-14	96/Rail
MC14013BDTR2	TSSOP-14	2500/Tape & Reel
MC14013BF	SOEIAJ-14	See Note 1.
MC14013BFEL	SOEIAJ-14	See Note 1.

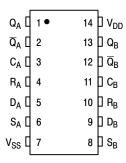
 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

**TRUTH TABLE** 

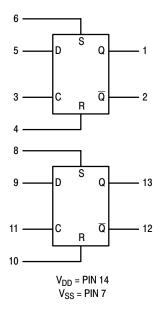
	Inp	Out	outs		
Clock†	Data	Reset	Set	Q	Q
	0	0	0	0	1
	1	0	0	1	0
~	Х	0	0	Q	Q
Х	Х	1	0	0	1
Х	Х	0	1	1	0
Х	Х	1	1	1	1

No Change

#### **PIN ASSIGNMENT**



### **BLOCK DIAGRAM**



X = Don't Care

<sup>† =</sup> Level Change

#### **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ <sup>(4.)</sup>	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or $V_{DD}$	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level	V <sub>IL</sub>	5.0 10 15	_	1.5 3.0 4.0	_	2.25 4.50 6.75	1.5 3.0 4.0	_	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I <sub>OH</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4	_ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		I <sub>in</sub>	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	_ _ _	1.0 2.0 4.0	_ _ _	0.002 0.004 0.006	1.0 2.0 4.0	_ _ _	30 60 120	μAdc
Total Supply Current (5.) (6 (Dynamic plus Quiesc Per Package) (C <sub>L</sub> = 50 pF on all outp buffers switching)	ent,	I <sub>T</sub>	5.0 10 15			$I_T = ($	.75 μΑ/kHz) 1.5 μΑ/kHz) f 2.3 μΑ/kHz) f	+ I <sub>DD</sub>	•		μAdc

<sup>4.</sup> Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
5. The formulas given are for the typical characteristics only at 25°C.
6. To calculate total supply current at loads other than 50 pF:

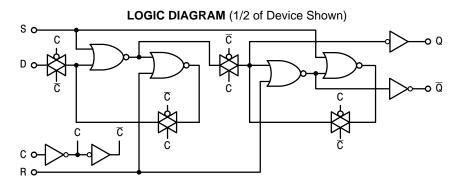
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

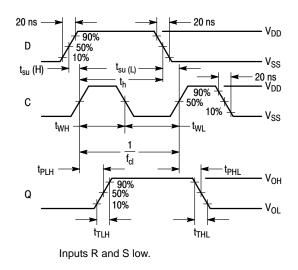
where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.002.

## SWITCHING CHARACTERISTICS (7.) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

Characteristic	Symbol	$V_{DD}$	Min	Тур (8.)	Max	Unit
Output Rise and Fall Time	t <sub>TLH</sub> ,					ns
$t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$	t <sub>THL</sub>	5.0	_	100	200	
$t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$		10	_	50	100	
$t_{TLH}$ , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t <sub>PLH</sub>					ns
Clock to Q, Q	$t_{PHL}$					
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 90 \text{ ns}$		5.0	_	175	350	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$		10	_	75	150	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 25 \text{ ns}$		15	_	50	100	
Set to Q, $\overline{Q}$						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 90 \text{ ns}$		5.0	_	175	350	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$		10	_	75	150	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 25 \text{ ns}$		15	_	50	100	
Reset to Q, Q						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 265 \text{ ns}$		5.0	_	225	450	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 67 \text{ ns}$		10	_	100	200	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 50 \text{ ns}$		15	_	75	150	
Setup Times (9.)	t <sub>su</sub>	5.0	40	20	_	ns
		10	20	10	_	
		15	15	7.5	_	
Hold Times (9.)	t <sub>h</sub>	5.0	40	20	_	ns
		10	20	10	_	
		15	15	7.5	_	
Clock Pulse Width	$t_{WL}$ , $t_{WH}$	5.0	250	125	_	ns
		10	100	50	_	
		15	70	35	_	
Clock Pulse Frequency	f <sub>cl</sub>	5.0	_	4.0	2.0	MHz
		10	_	10	5.0	
		15	_	14	7.0	
Clock Pulse Rise and Fall Time	t <sub>TLH</sub>	5.0	_	_	15	μs
	t <sub>THL</sub>	10	_	_	5.0	
		15	_	_	4.0	
Set and Reset Pulse Width	$t_{WL}$ , $t_{WH}$	5.0	250	125	_	ns
		10	100	50	_	
		15	70	35	_	
Removal Times	t <sub>rem</sub>					ns
Set		5	80	0	-	
		10	45	5	_	
		15	35	5	_	
Reset		5	50	- 35	_	
		10	30	- 10	_	
		15	25	- 5	_	

- The formulas given are for the typical characteristics only at 25°C.
   Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
   Data must be valid for 250 ns with a 5 V supply, 100 ns with 10 V, and 70 ns with 15 V.





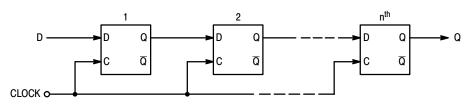
20 ns --20 ns  $V_{DD}$ SET OR 10% RESET  $V_{SS}$ 2<u>0 ns</u> V<sub>DD</sub> 20 ns CLOCK  $V_{SS}$  $t_{PLH}$  $t_{PHL}$  $V_{OH}$ Q OR  $\overline{Q}$ 50% · V<sub>OL</sub>

Figure 1. Dynamic Signal Waveforms (Data, Clock, and Output)

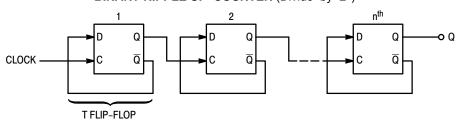
Figure 2. Dynamic Signal Waveforms (Set, Reset, Clock, and Output)

#### **TYPICAL APPLICATIONS**

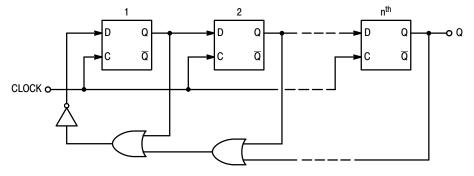
#### n-STAGE SHIFT REGISTER



#### BINARY RIPPLE UP-COUNTER (Divide-by-2<sup>n</sup>)



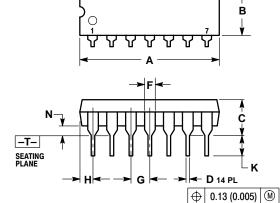
#### MODIFIED RING COUNTER (Divide-by-(n+1))

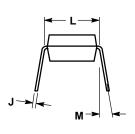


#### **PACKAGE DIMENSIONS**

#### **P SUFFIX**

PLASTIC DIP PACKAGE CASE 646-06 ISSUE M

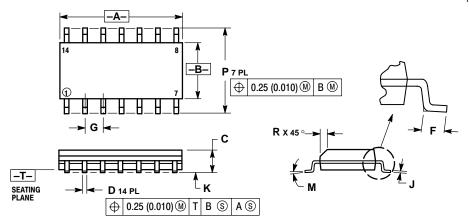




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. POLIMED CONDESS ORTIONAL
- 5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M		10°		10°
N	0.015	0.039	0.38	1.01

#### **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



#### NOTES:

- OTES.

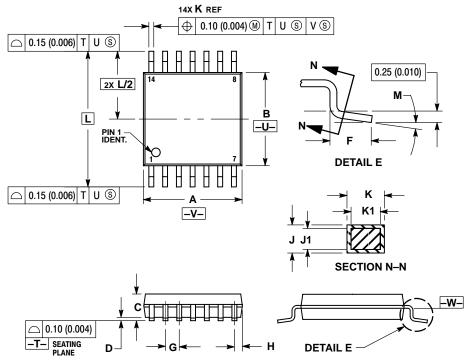
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PHOTHUSIUN U.15 (U.UUD) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

#### PACKAGE DIMENSIONS

#### **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948G-01 **ISSUE O**



#### NOTES:

- 1. DIMENSIS Y14.5M, 1982. DIMENSIONING AND TOLERANCING PER ANSI
- T14-3M, 1902.

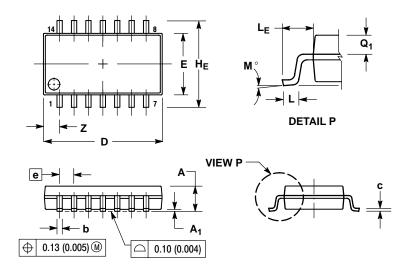
  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED
- 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT
- INTERLEAD FLASH OR PROTRUSION SHALL NO EXCEED
  0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- REFERENCE ONLY.

  '. DIMENSION A AND B ARE TO BE

DETERMINED AT DATUM PLANE -W						
	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.90	5.10	0.193	0.200		
В	4.30	4.50	0.169	0.177		
С		1.20		0.047		
D	0.05	0.15	0.002	0.006		
F	0.50	0.75	0.020	0.030		
G	0.65	BSC	0.026 BSC			
Н	0.50	0.60	0.020	0.024		
J	0.09	0.20	0.004	0.008		
J1	0.09	0.16	0.004	0.006		
K	0.19	0.30	0.007	0.012		
K1	0.19	0.25	0.007	0.010		
L	6.40 BSC		0.252			
M	0°	8°	0°	8°		

#### **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 965-01 **ISSUE O**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI DIMENSIONING AND TOLERANCING PER ( Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
- B. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- OH PHOTHUSIONS SHALL NOT EXCEED 0.15
  (0.006) PER SIDE.

  4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR DESTRUCTION. DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

  DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
$Q_1$	0.70	0.90	0.028	0.035
Z		1.42		0.056

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